

参与 2023 国 ~~际~~ 名 公
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		MEMS						
		1 2 3 4 5 6						
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	1		ZL201 01018 1105.3	2013 02 13	113503 8			
	2		ZL201 21051 4737.6	2015 09 16	178712 0			
	1		ZL201 01027 8255.6	2013 03 20	115723 6			
			ZL200 91019	2012 07 18	100514			

	3		6795.7		0			
	111		ZL201 31002 8123.1	2015 08 05	174579 6			
	2							
	SOI MEMS		ZL201 41019 1944.1	2016 04 06	201609 2			
	1							
		3	ZL200 81003 7306.9	2010 02 03	597434			
			ZL201 41016 5319.X	2016 05 25	208197 0			
	2							
	MEMS		ZL201 31001 2777.5	2015 09 23	179521 1			
	3							
	Semiconductor devices - Micro-electromechanical devices - Part 25: Silicon based MEMS fabrication technology - Measurement method of pull-press and shearing strength of micro bonding area		IEC 62047 -25	2016 9 1	/			